

What is claimed is:

1. A cap-shaped lid for use with a generally flat base to seal an electronic device comprising a top portion, a wall structure extending around an entire periphery of the top portion and having an upper end connected to the top portion
5 and a lower end, a lip connected to the lower end of the wall structure around an entire periphery of the wall structure and extending outwards from an outer surface of the wall structure by 10 - 500 μm , and solder applied to an inner surface of the lid on at least the portion of the cap-shaped lip.
2. A lid as claimed in claim 1 wherein the lip is curved with respect to the
10 wall structure.
3. A lid as claimed in claim 1 wherein the top surface of the lid is polygonal.
4. A lid as claimed in claim 1 wherein the wall structure extends substantially perpendicularly from the top surface.
- 15 5. A lid as claimed in claim 1 wherein solder is provided on an entire inner surface of the lid.
6. A packaged electronic part comprising a generally flat base, an electronic device mounted on a top surface of the base, and a cap-shaped lid according to claim 1 covering the electronic device and soldered to the top surface of the base.
- 20 7. A method of manufacturing a cap-shaped lid for a package for an electronic device comprising performing drawing of a metal sheet having solder on a first side of the metal sheet to form a recessed shape having a top portion, a wall structure extending from the top portion around an entire periphery thereof, and a flange extending outwards from the wall structure with the first side of the metal

strip on the interior of the recessed shape, and then severing the flange to define a lip extending around an entire periphery of the recessed shape and extending 10 - 500 μm from an outer side of the wall structure.

8. A method as claimed in claim 7 including severing the flange with a
5 punch.

9. A method as claimed in claim 7 including severing the flange in a portion which is curved with respect to the wall structure.

10. A cap-shaped lid for use with a generally flat base to seal an electronic device manufactured by the method of claim 7.